

LGA3647 · 1U SERVER CPU AIR COOLER

LGA3647-4B14

Copper base with heat pipes with copper fins for LGA3647 platforms in 1U server chassis. Final selection should be validated against chassis airflow, inlet air temperature, fan curve, mounting condition and CPU thermal limit.

LGA3647

1U SERVER

HEAT-PIPE

COPPER FINES

REF. LOAD UP TO 165 W



MAIN VIEW



VIEW 2

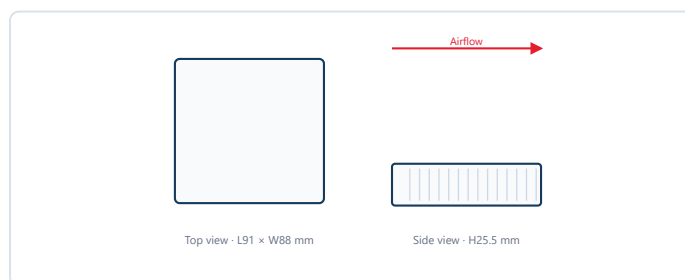
KEY SPECIFICATIONS

Product Model	LGA3647-4B14
Product Type	1U Server CPU Air Cooler
Socket / Platform	LGA3647(Square motherboard)
Overall Size	L91 x W88 x H25.5 mm
Mounting Hole Pitch	TBD
Fin Thickness	0.3 mm
Fin Spacing	1.75 mm
Reference Thermal Load	Up to 165 W, subject to system airflow validation
Weight	TBD

CONSTRUCTION

Base	Copper base with heat pipes
Fins	Copper fins
Material (as cataloged)	Copper & Aluminum & Heat Pipe
Fan	TBD
Bearing	TBD
Voltage	TBD
Surface Finish	TBD / per customer requirement
Airflow Direction	Front-to-back, subject to chassis ducting

MECHANICAL INTERFACE & DIMENSIONS



Mounting Hole Pitch: TBD

CPU Contact Area: TBD

Screw Type: TBD

Recommended Torque: TBD

Base Flatness: TBD

Keep-out Zone: per customer drawing

Mechanical compatibility must be confirmed against the customer motherboard, CPU socket keep-out zone, chassis height and mounting hardware.

THERMAL PERFORMANCE NOTES

Reference thermal load: 165 W. Final performance depends on airflow, inlet air temperature, fan curve, chassis ducting, CPU thermal limit, TIM condition and mounting pressure.

Thermal Resistance: TBD °C/W

Recommended Airflow: TBD CFM

Pressure Drop: TBD Pa

Test Condition: TBD

RFQ / PLATFORM DATA NEEDED

For accurate selection or quotation, please provide platform/socket, target heat load, chassis height (1U/2U/4U), available airflow, inlet air temperature, fan curve or pressure condition, mounting requirement and expected quantity. Drawings or 3D model welcome.